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Academic Details:

Sr. No.	Degree	University / Institution	CGPA / %age / Rank
1	Ph. D. (Mech. Engg.)	PU, Chandigarh	Not Applicable
2	M. Tech. (Design of Mech. Equip.)	IIT Delhi	9.733 CGPA Second Topper in Class
3	B. Tech. (Mech. Engg.)	GNDEC, Ludhiana	81.8 % University Gold Medalist

Teaching and Research Experience:

Sr. No.	University	From Date	To Date	Designation
1	Panjab University, Chandigarh, India	07.11.2021	Till Date	Professor (Academic Level 14)
2	Panjab University, Chandigarh, India	07.11.2018	06.11.2021	Associate Professor (Academic Level 13A)
3	Panjab University, Chandigarh, India	07.11.2015	06.11.2018	Assistant Professor (Academic Level 12)
4	Panjab University, Chandigarh, India	07.11.2010	06.11.2015	Assistant Professor (Academic Level 11)
5	Panjab University, Chandigarh, India	07.11.2005	06.11.2010	Assistant Professor (Academic Level 10)

Awards and Achievements:

1. Appeared in **World's Top 2% Scientists List published by Elsevier during September 2022**
2. **Funds generated through conferences during Covid Lockdown Period: INR 45,77,000/-**
3. **Coordinator** of 3rd International Conference on Aspects of Materials Science and Engineering 2022 (ICAMSE2022) in which delegates from more than **Thirty Countries** presented their papers
4. **Coordinator** of 2nd ICAMSE2021 in which delegates from more than **Twenty Countries** presented their papers
5. **Coordinator** of 1st ICAMSE2020 in which 131 authors from **IITs, NITs, DRDO, CSIO, SAIL** etc. presented their papers
6. **Scopus h-Index: 20**
7. **Granted patent number 202022101790** on "Microwave spark-based joining" awarded on 11.04.2022
8. **Guest Editor** of SCIE and Scopus Indexed Journals
9. **Coordinator** of "1st International Faculty Development Program on Research and Development in Materials Behaviour, Processing and Characterization Techniques" held online from 9th to 14th June 2020
10. **Zonal Vice-President (North)** of Association for Machines and Mechanisms India (2014-2018)
11. **Principal Investigator** of DSTRE funded Research Project titled "Real time damage identification and monitoring in structural building model through smart sensors" during 2019-2021. Project Status: Completed
12. **Co-Principal Investigator** of UGC funded Major Research Project titled "Development of efficient finite element model updating techniques" during 2013-2017. Project Status: Completed
13. **Best Research Paper Award** in Mech. Engg. by UIET (**Cash Prize of INR 10,000/-** during year 2016)
14. **FITT Best Industry related Project Award** by **IIT Delhi** (**Total cash Prize of INR 40,000/-** during year 2005)
15. **University Gold Medal** (for first position in University) in B. Tech. (Mech. Engg.) during 2003
16. **GATE Scholarship** (INR 5000/- per month) during M. Tech. at IIT Delhi during 2003-2005
17. **GATE - 2003** Percentile 99.20. GATE – 2003 All India Rank 205
18. **Topper** in regular university exams in all semesters during B. Tech. (Batch 1999-2003)

Research Guidance:

Ph.D. Guidance: 03 Degree Awarded, 01 Thesis Submitted, 04 Ongoing

M. Tech. Guidance: 13 Degree Awarded, 01 Ongoing

Research Interests:

Design and Manufacturing; Materials; Joining; Manufacturing; Composites; Finite element analysis

List of Publications: <https://www.scopus.com/authid/detail.uri?authorId=55729231000>

Editorial Roles:

- Journal of Process Mechanical Engineering (SAGE)
- Indian Journal of Engineering and Materials Sciences (NISCPDR)
- High Temperature Materials and Processes (De Gruyter)
- Sustainability (MDPI)
- Materials Today: Proceedings (Elsevier)
- Materials Science Forum (Trans Tech Publications Ltd.)

Reviewer Roles in SCI/SCIE Indexed Journals:

- Mechanical Systems and Signal Processing (Elsevier)
- Journal of Manufacturing Processes (Elsevier)
- Journal of Sound and Vibration (Elsevier)
- Materials and Design (Elsevier)
- Engineering Fracture Mechanics (Elsevier)
- Materials Characterization (Elsevier)
- Ain Shams Engineering Journal (Elsevier)
- IEEE Sensors Journal (IEEE)
- Nature Communications (Springer)
- Transactions of the Indian Institute of Metals (Springer)
- Journal of Bionic Engineering (Springer)
- Journal of Mechanical Science and Technology (Springer)
- Arabian Journal for Science and Engineering (Springer)
- Sadhana (Springer)
- Journal of Process Mechanical Engineering (SAGE)
- Journal of Automobile Engineering (SAGE)
- Journal of Low Frequency Noise, Vibration & Active Control (SAGE)
- Measurement and Control (SAGE)
- Advances in Mechanical Engineering (SAGE)
- Journal of Mechanical Engineering Science (SAGE)
- Indian Journal of Engineering & Materials Sciences (NISCAIR)
- Materials Research Express (IOPscience)
- Smart Structures and Systems: An International Journal (Techno-Press)
- Intelligent Automation & Soft Computing (TSP)
- Shock and Vibration (Hindawi)
- Metallurgical Research & Technology (EDP Sciences)
- Structural Engineering and Mechanics (Techno-Press)

Reviewer Roles in Scopus Indexed Journals:

- Journal of Advanced Joining Processes (Elsevier)
- International Journal of Lightweight Materials and Manufacture (Elsevier)
- Case Studies in Chemical and Environmental Engineering (Elsevier)
- International Journal on Interactive Design and Manufacturing (Springer)
- Emergent Materials (Springer)
- Advances in Materials and Processing Technologies (Taylor and Francis)
- Energy Storage (Wiley)
- International Journal of Manufacturing, Materials, and Mechanical Engineering (IGI Global)
- Engineering Research Express (IOPscience)
- Structural Durability and Health Monitoring (Tech Science Press)

Official visits abroad:

1. U.S.A. during 2014 for paper presentation during 32nd International Modal Analysis Conference (Visit financially supported by TEQIP-II funding at UIET)
2. Malaysia during 2003 for paper presentation during 2nd International Conference on Mechatronics (Visit financially supported by IIT Delhi)